PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Shigeki WAKASA	07/18/2008
Yasuharu ISHIKAWA	07/24/2008
Isao SOMA	07/24/2008
Hiroshi NAKAYAMA	07/18/2008

RECEIVING PARTY DATA

Name:	SONY CORPORATION	
Street Address:	1-7-1 Konan, Minato-ku	
City:	Tokyo	
State/Country:	Japan	
Postal Code:	108-0075	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12182418

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	329826US8
NAME OF SUBMITTER:	Tamika R. Gaston

Total Attachments: 2

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PATENT REEL: 021322 FRAME: 0103

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PATENT REEL: 021322 FRAME: 0104

Docket Number:

ASSIGNMENT
WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in INFORMATION PROCESSING APPARATUS AND METHOD AND INFORMATION PROCESSING SYSTEM
for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;
AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficience of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;
And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.
And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number:, Filing Date:
This assignment executed on the dates indicated below.
Shigeki WAKASA Shigeki WAKASA Name of first or sole inventor Execution date of U.S. Patent Application
Name of first or sole inventor Execution date of U.S. Patent Application
Kanagawa, Japan
Residence of first or sole inventor
Signature of first or sole inventor Signature of first or sole inventor Date of this assignment
Signature of first or sole inventor Date of this assignmen

PATENT REEL: 021322 FRAME: 0105

Signature of fifth inventor	Date of this assignment
Residence of fifth inventor	
Name of fifth inventor	Execution date of U.S. Patent Application
Signature of fourth inventor V	v v Date of this assignment
Signature of fourth inventor	July 18, 2008 Date of this assignment
Residence of fourth inventor	
Chiba, Japan	V
Name of fourth inventor	July 18. 2008 Execution date of U.S. Patent Application
Hiroshi NAKAYAMA	a.lu 18 2008
Signature of third inventor	Date of this assignment
Signature of third inventor	July 24, 2008
Residence of third inventor	N Pu ad = 8
Saitama, Japan	
Name of third inventor	Execution date of U.S. Patent Application
Isao SOMA	July 24, 2008
Signature of second inventor	Date of this assignment
ZX	July 24, 249 Date of this assignment
Residence of second inventor	
	Execution date of O.S. Patent Application
Yasuharu ISHIKAWA Name of second inventor	Execution date of U.S. Patent Application

PATENT REEL: 021322 FRAME: 0106

RECORDED: 07/31/2008